EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1623	257/787.ccls.	USPAT	OR	ON	2006/10/01 12:50
L2	0	((semiconductor with device) and (substrate with main with first) and (third with second) and (protective adj film) and (shape with angle) and (second with (protective adj film)) and (die adj bonding adj layer) and (semiconductor adj chip) and (die with protective with second) and (sealing adj resin) and ((bottom adj surface) with second)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/01 12:54
S1	3278	((ball adj grid adj array) or BGA) and substrate and chip and adhesive and insulat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:46
S2	2265	S1 and thermal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:46
S3	2075	S2 and wir$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:47
S4	65	S3 and ((die adj bonding) with layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:14
S5	0	S1 and (((chip or die) adj bonding) with ahesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:15
S6	180	S1 and (((chip or die) adj bonding) with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:34
S7	62	S6 and bonding.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:34

EAST Search History

S8	3	("4933030" | "5391604" | "6175152").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/02 12:13
S9	0	("6552421").URPN.	USPAT	OR	ON	2005/09/02 13:00
S10	1471	257/787.ccls.	USPAT	OR	ON	2006/10/01 12:50
S11	1087	257/678.ccls.	USPAT	OR	ON	2005/09/02 14:09
S12	1111	257/777.ccls.	USPAT	OR	ON	2005/09/02 14:09